

Data Sheet



Shenzhen Deyan Electronics Co., Ltd

1. Scope:

This specification applies the Shielded construction chip inductor DNR5040S470MT

2. Outline:

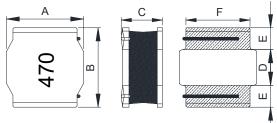
The products are used as choke coils for DC/DC converter and consist of drum core, coil, magnetic glue and terminals.

3. Safety Specification:

The products shall be used as secondary circuit parts, thus are not applied by any specific safety standards.

4. Specification:

4.1. Dimensions



Α	5.0±0.3	D	2.5 Ref.
В	5.0±0.3	Е	1.25 Ref.
С	4.0 Max.	F	4.0 Ref.

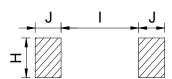
4.2. Main parts list

No.	Part name	Material	Qty
1	Drum Core	Ni-Zn Ferrite or Equivalent	1set
2	Coil	Cu/P180/Grand 1/Polyurethane enameled or Equivalent	1set
3	Solder	107H or Equivalent	0.04 g
4	Magnetic Glue	Ferrite Powder & Resin	0.04 g

4.3. Pin Connection:



4.4. Recommended Land Pattern:



Н	4.2 Ref.
I	2.3 Ref.
J	1.4 Ref.

4.5. Electrical Specifications:

Part Number	Rated Inductance (1) (µH)	Test Condition	DC Resistance (mΩ)	Self -Resonant Frequency (MHz) Min.	Isat (2) Amperes (A)	Irms(3) Amperes (A)	Part Marking Designator
DNR5040S 470M T	47±20%	100kHz,1Vrms	354Мах. 289Тур.	7	1.10Мах. 1.20Тур.	1.00Max. 1.25Typ.	470

⁽¹⁾ Open Circuit Inductance Test Parameters: 100kHz, 1.0Vms, 0.0Adc.

proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

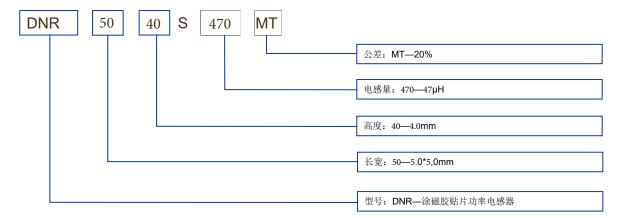
Note: The rated current is subject to change depending on the cooling

⁽²⁾ Isat Amperes Typical for approximately 30% roll off (@25°C)

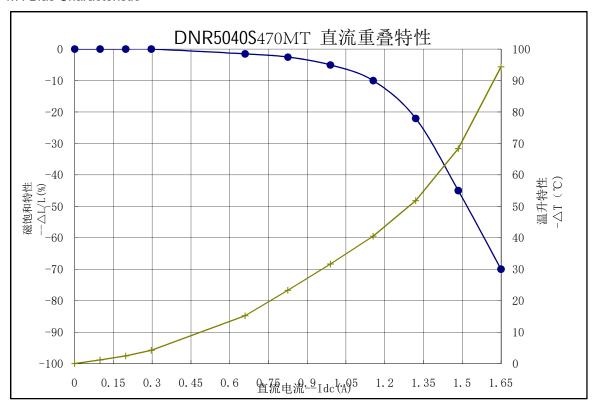
⁽²⁾ Isas: Aniperes Typical of approximately 30 / 10 for five 20 C) (3) Irms: current for an approximate ΔT of 40 °C without core loss s(Ta=25 °C). It is recommended that the temperature of the part not exceed 125 °C. PCB layout, trace thickness and width, air-flow, and

⁽⁴⁾ Rated current: Isat and Irms whichever is lower.

4.6. Ordering Code & Explanation of Part Numbers:



4.7. Bias Characteristic

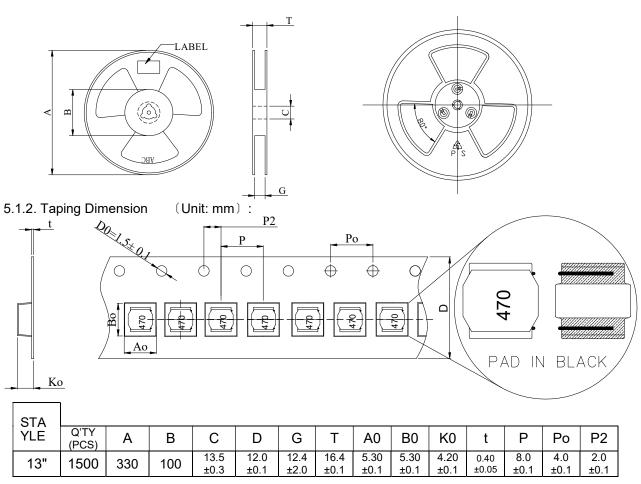




5. Package Specification:

5.1. Taping Specification:5.1.1.Reel Dimension

(Unit: mm):



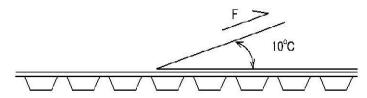
5.1.3. Tensile Strength: 5.1.3.1. Plastic tape: \geq 10N (\geq 1.0kgf)

5.1.3.2.Material : PS

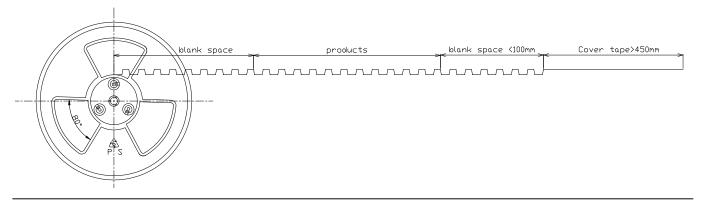
5.1.3.3.Cover tape : $\geq 5N$ (≥ 0.5 kgf)

5.1.4. Tensile Strength of Cover Tape (Ref.): F=0.2 \sim 0.9N

Angel of pull 0 \sim 15 $^{\circ}$ opposite the forward direction, Velocity of pull: 300 mm/min.

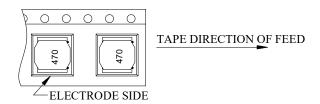


5.1.5. Packing Style of Taping (Unit: mm)





5.1.6. Packaging Style of Products:

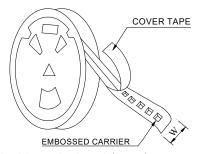


5.1.7. Packaging style of case

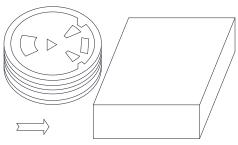
5.1.7.1. Packing cases are composed of the inner case and outer case.

5.1.7.2. Nine inners cases are put in an outer, thus 13,500 products put in an outer case.

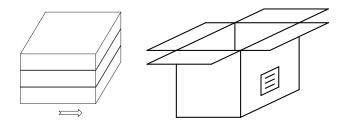
5.1.7.3. Paper cushion are placed on the upper and bottom side in the outer case



1,500 pcs in 1 reel (inner) case



3 reels in 1 reels (inner) cases



3 reels (inner) cases in 1 packaging (outer) case

5.1.8. Indication:

5.1.8.1. Label attached on reel:

Production Label

Qty.:1,500pcs

Lot No.:20171206N03

Made in China

5.1.8.1. Label attached on packaging (outer) case:

Production Label

Qty.:13,500pcs

Lot No.:20171206N03

Made in China

5.1.9. Notes:

5.1.9.1. This specification defines the standard packaging style and is subject to change depending on quantity or fractions.

5.1.9.2. Inside of cases shall be filled with cushions to keep the products stable.

5.1.9.3. Inspection Certificate: Attach size data and the electric characteristic result for each shipping lot as "Inspection Certificate".



6. Reliability data:

Item	Specified Value	Test Method and Remarks
1.Operating Temperature Range	-40℃~+125℃	Including self-generated heat.
2. Storage Temperature Range	-40°C ~+125°C	0 ∼ 40 $^{\circ}$ for the product with taping.
3.External Appearance	The coil has no external defects.	On visual inspection.
4.Rated current	Within the specified tolerance	The maximum DC value having inductance decrease within
	, i	specified value and temperature increase within 40°C by the application of DC bias.
		Inductance decrease.(Type: 30%)
5.Inductance	Within the specified tolerance	LCR Meter: HP 4194A or equivalent, 100KHz, 0.25V
6.DC Resistance	Within the specified tolerance	DC ohmmeter: TOS8001 or equivalent.
	· ·	·
7.Self resonance	Within the specification	Impedance analyzer/material analyzer: HP4291A ,
frequency	ļ.,.,	HP4194A, 4192A or equivalent.
8.Temperature characteristic	Inductance change: Within $\pm 15\%$ 0 ~ 2000 ppm/ $^{\circ}$ C	Measurement of inductance shall be taken at temperature range within -40 \sim +125 $^{\circ}$ C.
		With reference to inductance value at $+25^{\circ}$ C, change rate shall be calculated.
		Change of maximum inductance deviation in step 1 to 5
		Temperature at step 1: 25°C
		Temperature at step 2: Minimum operating temperature
		Temperature at step 3: 25°C (Standard temperature)
		Temperature at step 4: Maximum operating temperature
		Temperature at step 5: 25 °C and the value calculate based
		on the value applicable in a normal temperature and norma
		humidity shall be $\triangle L/L_{25\%} \leqslant \pm 15\%$
		Measurement Equipments: HP 4194A(at 100 KHz) or
		equivalent.
9.Resistance to flexure	Inductance change: Within±5.0%	The test samples shall be soldered to the test board by the
9.Resistance to flexure of substrate	Inductance change: Within±5.0% There shall be no mechanical damage or	The test samples shall be soldered to the test board by the reflow.
		reflow.
	There shall be no mechanical damage or	reflow. As illustrated below, apply force in the direction of the arrow
	There shall be no mechanical damage or	reflow. As illustrated below, apply force in the direction of the arrow
	There shall be no mechanical damage or	reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 3 mm
	There shall be no mechanical damage or	reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 3 mm Test board size: 100*40*1.0 Test board material: glass
	There shall be no mechanical damage or	reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 3 mm Test board size: 100*40*1.0 Test board material: glass epoxy-resin
	There shall be no mechanical damage or	reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 3 mm Test board size: 100*40*1.0 Test board material: glass epoxy-resin Solder cream thickness: 0.12mm.
	There shall be no mechanical damage or	reflow. As illustrated below, apply force in the direction of the arrow indicating until deflection of the test board reaches to 3 mm Test board size: 100*40*1.0 Test board material: glass epoxy-resin Solder cream thickness: 0.12mm. Keep time: 3~5seconds Speed:0.5mm/sec Force Rod 10 20



Item	Specified Value	Test Met	thod and R	emarks	
10.Insulation resistance	NL	Between Coils			
11.Insulation resistance	Over 100M Ω at 100V D.C. for 1 minute.	Between coil and core. DC 100V voltage shall be applied for			
		1 minuteacross the top s	surface an	d the terminal of this	
		sample(current: 1 m A)			
12.Withstanding voltage	No dielectric breakdown at 100V D.C. for 1	Between coil and core. DO	C 100V vol	tage shall be applied fo	
	minute	1 minuteacross the top s	surface an	d the terminal of this	
		sample(current: 1 m A)			
13.Adhesion of terminal	Shall not come off PC board.	The test samples shall be soldered to the test board by the			
electrode		reflow.		·	
		Applied force: 10N to X ar	nd Y direct	ons. Duration: 5s.	
		Solder cream thickness: 0			
		□ □ 10	N, 5s		
			$\overline{\chi}$		
		\\^\^			
		Y			
14.Resistance to	Inductance change: Within±10%	The test samples shall be	soldered t	o the test board by the	
vibration	There shall be no mechanical damage.	reflow.			
		Then it shall be submitted	to below t	est conditions.	
		The test samples shall be	soldered t	o the test board by the	
		reflow.			
		Then it shall be submitted	to below t	est conditions.	
		Frequency Range	10~5	55Hz	
		Total Amplitude	1.5mr	m(May not exceed	
			accel	eration 196 m/s ²)	
		Sweeping Method	10Hz	to 55Hz to 10 Hz for	
			1 min		
		Time	X	For 2 hours on	
			Υ	each X, Y, and Z	
			Z	axis.	
		Recovery: At least 2hrs of	-		
		condition sfter the test, fol	lowed by t	he measurement within	
		48 hrs.			
15.Solderability	At least 90% of surface of terminal electrode is	The test samples shall be dipped in flux, and then sh		flux, and then shall be	
	covered by new solder.	preheated for 2 minutes in	n a tempera	ature of 135 \sim 150 $^{\circ}{\!$	
		and after it has been imme	ersed to	a depth 0.5mm below	
		for 5.0 ± 1.0 seconds molt	en solder a	as shown in below table	
		Flux: Methanol solution co	ontaining ro	osin 25%.	
		Solder Temperature: 245:	±5℃		
		Immersion depth: 0.5mm	l.		



Item	Specified Value	Test Method and Remarks			
16.Resistance to	Inductance change: Within±10%	The test sample shall be exposed to reflow oven at 230 \pm			
soldering heat	No significant abnormality in appearance.	$5^\circ\!\mathbb{C}$ for 40 seconds, with peak temperature at $260\!\pm\!5^\circ\!\mathbb{C}$ for			
		5 seconds, 2 times.			
		Test board thickness: 1.0 mm			
		Test board material: glass epoxy-resin.			
		Reflow condition (temperature chart,)			
		250			
		200 230°C.40s			
		150 100			
		50			
		0 L			
17.Thermal shock	Inductance change: Within±10%	The test samples shall be soldered to the test board by the			
	No significant abnormality in appearance.	reflow. The test samples shall be placed at specified			
		temperature for specified time by step 1 to step 4 as shown			
		in below table in sequence.			
		The temperature cycle shall be repeated 100 cycles.			
		Conditions of 1 cycle			
		Step Temperature(°C) Duration(min)			
		1 -40±3 30±3			
		2 Room temperature Within 3			
		3 +85±2 30±3			
		4 Room temperature Within 3			
40 Dames hand	Industrial ACC	Recovery : At least 2hrs of recovery under the standard			
18.Damp heat	Inductance change: Within±10%	condition after the test, followed by the measurement within			
	No significant abnormality in appearance.	48 hrs.			
		The test samples shall be soldered to the test board by the			
		reflow.			
		The test samples shall be placed in thermostatic oven set at			
		specified temperature and humidity as shown in below table.			
		Temperature 60±2°C			
		Humidity 90~95%RH			
		Time 500±24hour			
19.Loading under damp	Inductance change: Within±10%	Recovery: At least 2hrs of recovery under the standard			
heat	No significant abnormality in appearance.	condition after the test, followed by the measurement within			
nout	No significant abnormality in appearance.	48 hrs.			
		The test samples shall be soldered to the test board by the			
		reflow.			
		The test samples shall be placed in thermostatic oven set at			
		specified temperature and humidity and applied the rated			
		current continuously as shown in below table.			
		Temperature 60±2°C			
		Humidity 90~95%RH			
		Time 500±24hour			
		111116 300 ± 24110u1			



Item	Specified Value	Test Me	ethod and Remarks
20.Low temperature life	Inductance change: Within±10%	Recovery: At least 2h	rs of recovery under the standard
test	No significant abnormality in appearance.	condition after the test, for	ollowed by the measurement with
		48 hrs.	
		The test samples shall be	e soldered to the test board by th
		reflow.	
			es shall be placed at test condition
		as shown in below table.	
		Temperature	-40±3℃
		Time	500 ± 24hour
21.High temperature life	Inductance change: Within±10%	Recovery: At least 2h	rs of recovery under the standard
test	No significant abnormality in appearance.	condition after the test, for 48 hrs.	ollowed by the measurement with
		Temperature	125±3 ℃
		Time	500±24hour
22.Loading at high	Inductance change: Within±10%	-	e soldered to the test board by the
temperature life test	No significant abnormality in appearance.	reflow soldering.	
		Temperature	85±3℃
		Applied current	Rated current
		Time	500 ± 24 hour
23.Standard condition	Standard test condition: Unless otherwise specified, temperature is $25\pm15^\circ\mathbb{C}$ and $65\pm20\%$ of relative humidity. When there are question concerning measurement result: In order to provide correlation date, the test shall be condition of $25\pm2^\circ\mathbb{C}$ of temperature, $65\pm5\%$ relative humidity. Inductance is in accordance with our measured value.		



Item	Specified Value	Test Method and Remarks
24.Heat endurance of	Electric no variation Appearance no deformation.	Reflow hart endurance test (temperature chart.)
reflow soldering	Inductance change: Within \pm 10 %	300
	No significant abnormality in appearance.	The test should be made under the conditions according to the chart, after the test it is kept for 2 hours under the normal temperature and humidity. Then, no mechanical and electrical defect should be found out. The reflow test can be done twice, but the interval should be more than one hour under the normal conditions. The reflow test conditions are based on the testing instruments available in VCOIL.

7. Others:

- 7.1. The contents of this document only assures the characteristics and quality of the sole components. Regarding its use, please evaluate and check that they work correctly when fixed to your equipments.
- 7.2. We will not take any responsibility for any troubles caused by usage beyond the range that this document specifies.
- 7.3. The products in this specification are targeted for use in general electrical equipments. Please do not apply on equipments that need. Especially high reliability and/or the defects caused by the product will have direct influence on a person's life or property.
- 7.4. Period of quality assurance shall be 1 year from the date of shipment. The products must be controlled normal conditions, thus in cases where the products are put under abnormally high temperature and humidity or contamination and damage by natural disasters or other reasons, the above quality assurance period will not be valid.
- 7.5. Please return this document with signature of receipt within 30 days after our issued date. In case this document is not returned with signature of receipt within 30 days, it is seen as you have approved this document.
- 7.6. When additions or modifications are needed to this document, both parties shall discuss the revision of the document.
- 7.7. Both parties are under confidentiality obligation regarding the information contained in this document.

